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Thermo-Mechanical Optimization of Photon Shutter 1 for APS Front Ends

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Abstract

Photon shutter 1 (PS1) is one of the most critical elements on the front end of the beamlines at the Advanced Photon Source (APS) now under construction at Argonne National Laboratory (ANL). The PS1 uses an enhanced heat transfer tube developed at ANL. Due to large thermal loads on these components, inclined geometry is used in the design to spread the footprint of the x-ray beam. Even then, thermal loads are very critical. To address the thermal and thermo-mechanical issues, analytical studies have been applied to a simplified model of the shutter tube. The maximum temperature and maximum effective stress have been parametrically studied. Results for maximum temperatures and stresses are obtained and compared with the available strength/fatigue data for the materials proposed for the shutter design.

1 Introduction

Photon Shutter 1 (PS1) is one of the most critical elements on the insertion device (ID) front end [1] of the beamlines at the Advanced Photon Source (APS) now under construction at Argonne National Laboratory (ANL). The PS1 uses an enhanced heat transfer tube developed at ANL [2]. Due to large thermal loads on these components, inclined geometry is used in the design to spread the footprint of the x-ray beam. Even then, thermal loads are very critical. To address the thermal and thermo-mechanical issues, analytical studies [3] have been applied to a simplified model of the shutter tube. The front-end design includes a pair of fixed masks (FM) and another pair of photon shutters (PS). The FMs contain the x-ray beam, whereas the PSs fully intercept it. However, both are designed to withstand the x-ray beam coming off the most powerful APS ID, currently, a 2.5 m long undulator designated Undulator A. The 2.5 m long Undulator A has a total power of 5.2 kW. Future plans for the APS include a 5 m long Undulator A with a total power of 10.4 kW. This paper deals with x-rays from the 2.5-m ID. However, the analysis will be extended to the future 5-m device.

Research, development, and analysis on FMs and PSs have much in common. The FM and The PS share a similar flow tube that offers a highly enhanced heat transfer feature [2]. The FM is a box-like aperture with tapered vertical and horizontal sides. The sides are composed of the enhanced heat transfer tube set at small grazing angles to the beam. The PS, on the other hand, is built like a "hockey stick" coil set horizontally at a small grazing angle of 1.5 to 2 degrees to the beam. Therefore, the horizontal tubes of both the FM and the PS share the same analysis.

Because the high energy photon beam striking these components will result in large temperature gradients and stresses, it is necessary to analyze not only the temperature field but also the resulting thermal stresses. The x-ray beam has a complex profile, Gaussian in the vertical direction and parabolic in the horizontal direction as shown in Fig. 1 [4]. An analysis using the closed form solution has been carried out with a Gaussian beam profile spread in the horizontal plane at a grazing angle. An analysis using ANSYS-applied real-beam-profile strikes on these components was carried out to verify the analytical solution.

Both Glidcop [5] and oxygen-free copper (OFC) are used to build the structures of these components. Glidcop has much better fatigue strength above 150° C than does OFC [6]. The purpose of using a Glidcop plate is to let the beam strike the Glidcop surface, while the OFC acts as a cooling sub-structure. (The Glidcop plate is bonded to the OFC sub-structure.)

2 Nomenclature

```
T:
                          (°C)
         Temperature
         Stress Component
                                 (MPa)
\sigma_{ij}:
k:
         Thermal Conductivity
                                     (W/m \cdot {}^{\circ}C)
XYZ:
        Fixed Coordinate
                        (W/m^2)
        Heat Flux
q:
         Thickness of Plate
t:
                                                     (W/m^2 \cdot {}^{\circ}C)
         Convective Heat Transfer Coefficient
h:
                                     (assumed to be 32.2°C)
T_{\infty}:
         Ambient Temperature
1:
        Length of the Plate
                                  ( m)
         Width of the Plate
                                 (m)
b:
         Width where q Applied to Absorber
                                                     (m)
a:
         Standard Deviation (m)
r_o
         Poisson's Ratio
\nu:
                                               m/m^{\circ}C \times 10^{-6}
         Thermal Expansion Coefficient
\alpha_t:
```

3 Analytical Solution

The closed form analytical solution was developed for a simplified model using Gaussiandistributed heat flux. The channel tube is stretched into a plate, keeping the water-cooled area constant [2]. The thermal-analytical model can be applied to any thermal beam. In the following section, the energy equation, boundary conditions, and solution are described. The model does provide a good approximation for the channel tube. Consequently, the thermal stress and the deformation can also be expressed and approximated in closed form. From these equations, we can follow parametrically the trend of the thermal gradient and the thermal stress due to the temperature field created by the beam.

3.1 Temperature Field

A two-dimensional, steady-state boundary value problem was assumed in our analysis [3]. Because properties of Glidcop and OFC are similar, we assumed they are a single material. Hence, the heat equation is

$$\frac{\partial^2 T}{\partial x^2} + \frac{\partial^2 T}{\partial y^2} = 0. \tag{1}$$

The boundary conditions are

$$-k\frac{\partial T}{\partial y}(x,0) = q_o exp\left(-\frac{x^2}{r_o^2}\right) \quad 0 \le x \le a.$$

$$-k\frac{\partial T}{\partial y}(x,0) = 0 \qquad a < x \le b$$

$$-k\frac{\partial T}{\partial y}(x,t) = h_c(T - T_\infty)$$

$$\frac{\partial T}{\partial x}(0,y) = \frac{\partial T}{\partial x}(b,y) = 0.$$
(2)

The solutions give

$$\theta = C_o \left[\eta - 1 - \frac{1}{Bi} \right] + \sum_{m=1}^{\infty} C_m e^{-\lambda_m \eta} \cos(\lambda_m \xi) \left[1 + \frac{\lambda_m - Bi}{\lambda_m + Bi} e^{2\lambda_m (\eta - 1)} \right], \quad (3)$$

where

$$\alpha = \frac{a}{t}, \quad \beta = \frac{b}{t}, \qquad \xi = \frac{x}{t}$$

$$\eta = \frac{y}{t}, \quad \theta = \frac{k(T - T_{\infty})}{qt}, \quad Bi = \frac{h_{c}t}{k},$$
(4)

$$C_o = -\frac{r\sqrt{\pi}}{2\alpha} erf\left(\frac{\alpha}{r}\right),\tag{5}$$

where erf(...) is known to be the error function defined by [7] and

$$C_{m} = -\frac{\sqrt{\pi} r exp\left(-\frac{r^{2}\lambda_{m}^{2}}{4}\right) Re\left[erf\left(\frac{2\alpha + ir^{2}\lambda_{m}}{2r}\right)\right]}{\lambda_{m}\alpha\left(-1 + e^{-2\lambda_{m}}\frac{\lambda_{m} - Bi}{\lambda_{m} + Bi}\right)}, \quad \lambda_{m} = \frac{m\pi}{\beta}, \quad m \in N. (6)$$

Re(z) is the real part of the complex variable z; i is the imaginary number defined by $\sqrt{-1} = i$.

3.2 Stress Field

The magnitude of the cross section $(xy \ plane)$ of the photon shutter is much smaller than that of the length $(z \ axis)$. Therefore, the photon shutter behaves as a thermoelastic beam that is subject only to thermal loading.

The practical analysis of elastic beams under thermal loading is usually performed under Bernoulli-Euler rules [8]. That is, sections that are plane and perpendicular to the axis before loading remain so after loading, and the effect of lateral contraction may be neglected. The only nonzero stress component is σ_{zz} , which satisfies [8]:

$$\left(\frac{\partial^2}{\partial \xi^2} + \frac{\partial^2}{\partial \eta^2}\right) (\bar{\sigma}_{zz} + \gamma \theta) = 0,$$
(7)

where

$$\bar{\sigma}_{zz} = \frac{\sigma_{zz}}{E}, \qquad \gamma = \frac{\alpha_t qt}{k}.$$
 (8)

For any cross section, the total force and moments have to be in equilibrium. That is,

$$\int \sigma_{zz} dA = \int \sigma_{zz} \xi dA = \int \sigma_{zz} \eta dA = 0, \tag{9}$$

where $\int ...dA$ denotes the area integral over the cross section.

From Eq. (7), the general solution is

$$\bar{\sigma}_{zz} = -\gamma \theta + k_0 + k_1 \xi + k_2 \eta,\tag{10}$$

where

$$k_0 = 7a_0 - 3a_1 - 3a_2$$
, $k_1 = -\frac{6a_0 - 6a_1}{\alpha}$, $k_2 = -6a_0 - 6a_2$,

and

$$a_{0} = \frac{\gamma r \sqrt{\pi}}{2\alpha} \left(\frac{1}{2} + \frac{1}{Bi}\right) erf\left(\frac{\alpha}{r}\right)$$

$$a_{1} = \frac{\gamma r \sqrt{\pi}}{2\alpha} \left(\frac{1}{2} + \frac{1}{Bi}\right) erf\left(\frac{\alpha}{r}\right) - \frac{4\gamma r \sqrt{\pi}}{\alpha^{3}}$$

$$\sum_{m=1,3,5,\dots}^{\infty} \frac{exp\left(-\frac{r^{2}\lambda_{m}^{2}}{4}\right) Re\left[erf\left(\frac{2\alpha + ir^{2}\lambda_{m}}{2r}\right)\right]}{\lambda_{m}^{4}} \left(1 - \frac{2Bie^{-\lambda_{m}}}{(\lambda_{m} + Bi) - e^{-2\lambda_{m}}(\lambda_{m} - Bi)}\right)$$

$$a_{2} = \frac{\gamma r \sqrt{\pi}}{2\alpha} \left(\frac{1}{3} + \frac{1}{Bi}\right) erf\left(\frac{\alpha}{r}\right).$$
(11)

For more details about the analysis please refer to [3].

4 Numerical Solution

A three-dimensional finite element analysis was carried out to verify the closed form solution for APS front-end components. The convective heat transfer coefficient has a minimum value of $3 \frac{W}{cm^2} \cdot {}^{\circ}\text{C}$ [2], which is used in the finite element code ANSYS to verify the results from the closed form.

5 Results and Discussion

The parameters that are used in the analysis are as follows:

The Power from 2.5-m Undulator A	Q	5000 W
Conductivity of Glidcop	\check{K}	365 W/(m °C)
Conductivity of OFC	K	$391 \ W/(m \ ^{\circ}C)$
Young's Modulus of Glidcop	E	$1.3 \times 10^5 \mathrm{\ MPa}$
Young's Modulus of OFC	E	$1.15 \times 10^5 \mathrm{\ MPa}$
Thermal Exp. Coef. of Glidcop	α	$16.6 \times 10^{-6} \frac{1}{{}^{\circ}C}$
Thermal Exp. Coef. of OFC	α	$17.7 \times 10^{-6} \frac{1}{{}^{\circ}C}$
Poisson Ratio (Closed Form)	ν	0
Poisson Ratio of Glidcop	ν	.33
Poisson Ratio of OFC	ν	.343
Incident Beam Angle	θ	1.5°
Distance from the Source	l	$18.13\ meter$
Peak Power	q_0	$13.1 \frac{W}{mm^2}$

The x-ray beam has a complex profile, Gaussian in the vertical direction and parabolic in the horizontal direction. In order to use the closed form solution described above, we have to fit the beam power (shown in Fig. 1), which strikes the PS1, to a Gaussian-distributed heat flux. By using the least squares method, we found the standard deviation for the power at different distances and angles.

Figures 2 and 3 show the maximum temperature on the heating surface and cooling channel wall of the Glidcop material, respectively. From Fig. 2, we note that the maximum temperature has an optimal value. For example, for $h = 3 \text{ W}/(cm^2 \, ^{\circ}C)$, the optimal thickness is 5 mm to obtain a minimum surface temperature of about 197 $^{\circ}C$. Lower temperatures can only be obtained with higher "h" above $3 \text{ W}/(cm^2 \, ^{\circ}C)$. From Fig. 3, it is seen that, under these conditions, the maximum cooling channel temperature will be about 115 $^{\circ}C$. Increasing the channel wall thickness (Glidcop plus OFC) from 5mm to 10mm will help reduce the cooling channel wall temperature to 85 $^{\circ}C$ while keeping the maximum

temperature about the same (200 $^{\circ}C$).

The effective stress from the closed form solution was calculated based on the assumption that the tube was stretched into a flat plate. Figure 4 shows the maximum effective stress on the Glidcop surface. The slopes of the maximum effective stress curves matches the maximum temperature curves as expected.

Interfacial stress calculations for the closed form are addressed next. Calculation of the stress at the bonding surface was based on a single material. Normally, stress discontinuity will occur at the bonding surface due to differences in material properties, such as the thermal expansion coefficients and Young's moduli. It is tedious to derive solutions to reconcile discontinuity in stress at the bonding surface. Figure 6 shows the trend of the stress at the bonding surface if both materials have exactly the same properties. Note that, in the closed form solution for two layer materials, the interface is expected to have higher stress than that presented here.

The PS1 of the front end is composed of two different materials, Glidcop and OFC. Glidcop has much better strength above 150° C. The purpose of using a Glidcop plate is to allow the beam to strike the Glidcop surface; the OFC acts as the cooling sub-structure. Figures 5 and 6 show the maximum temperature and maximum effective stress, respectively, at the bonding surface for a 3.175 mm thick OFC tube. Copper sponge is brazed to the inside of the OFC tube, and a Glidcop face plate is bonded to the outside surface of the OFC. During the brazing/bonding process, the tensile strength of OFC drops. Figures 7 and 8 show the softening curves for OFC. It is, therefore, worthwhile to optimize the Glidcop thickness to reduce the maximum effective stress on OFC to a minimum when the beam strikes. Because thermal fatigue data for the OFC are not available at this time, it is desirable to keep the temperature and thermal stress low to attain a safety factor of 4 or better without considering the thermal fatigue in OFC. For example, for $h = 3 W/(cm^2 {}^{\circ}C)$, with a 3mm thick OFC tube, increasing the thickness of Glidcop from 3mm to 6mm not only decreases the maximum temperature from 135 ${}^{\circ}C$ to 108 ${}^{\circ}C$ but also decreases the maximum effective stress from 137 MPa to 95 MPa at the bonding surface.

Fig. 9 shows the temperature distribution from ANSYS calculations. The finite element model of PS1 has four thousand nodes and three thousand elements.

Table 1 lists the comparative results between the closed form and ANSYS solutions. Both methods agree within 5%. The optimized values of maximum stress show some discrepancies due to the difference between the real beam profile (ANSYS) and a curve-fit Gaussian profile (closed form). Nevertheless, the trend from ANSYS is such that the thicker the layer of Glidcop, the lower the maximum effective stress will be when the real beam profile is used. The total material thickness is kept between 6.25 mm to 9.5 mm for the ANSYS calculations.

Table 1. PS1,
$$h = 3 \frac{W}{cm^2 \circ C}$$
, 5Kw

	Closed Form			ANSYS			
	(Curve-Fit Gaussian Profile)			(Real Beam Profile)			
Thickness of Glidcop mm	t = 3.175	t = 4.5	t = 6.35	t = 3.175	t = 4.5	t = 6.35	
Max. Temperature							
on the surface ($^{\circ}C$)	198	200	202	187	186	185	
Max. Temperature							
on the cooling channel ($^{\circ}C$)	104	96	87	95	84	75	
Max. Stress on							
Glidcop surface (MPa)	236	240	243	247	242	233	
Max. Temperature							
on the bonding surface ($^{\circ}C$)	132	118	107	130	110	95	
Max. Stress on the							
bonding $surface(MPa)$	115	80	55	137	103	75	

6 Conclusion

From Table 1, we know that the maximum effective stress at the Glidcop surface is about 240 MPa regardless of the total thickness. Figure 10 shows the softening resistance of Glidcop AL-15 versus that of OFC and zirconium copper. The Glidcop face plate of PS1 has a safety factor about 2 without considering thermal fatigue. Currently, research in this area shows that Glidcop can be subjected to high temperature (870 °C) braze thermal cycles without damage. Figure 11 shows the tesnsile properties of Glidcop AL-15 under braze thermal cycles [6]. According to Fig. 11, the Glidcop face plate has at least a safety factor of 1.5 under thermal cycles because our maximum temperature (about 187 °C) is much lower than 870 °C.

The safety factor related to bonding and the OFC tube is not an issue if we can optimize the Glidcop thickness as described above.

7 Acknowledgments

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Figure 1: The Power Distribution of X-ray Beam Strikes on PS1

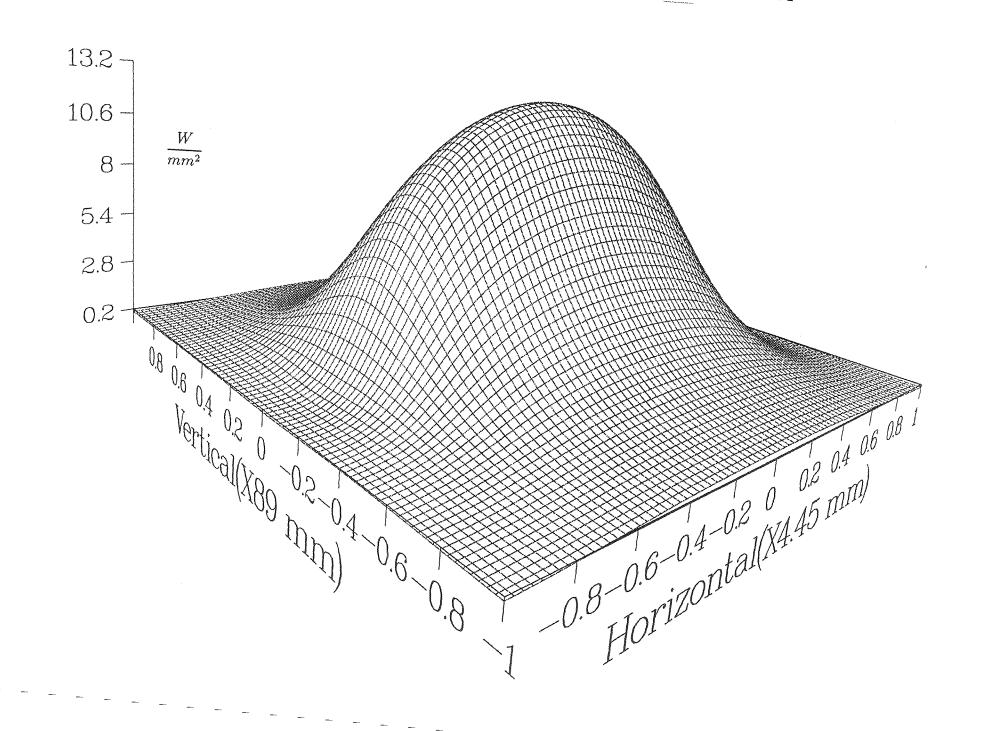


Figure 2: Maximum Surface Temperature for Glidcop (PS1)

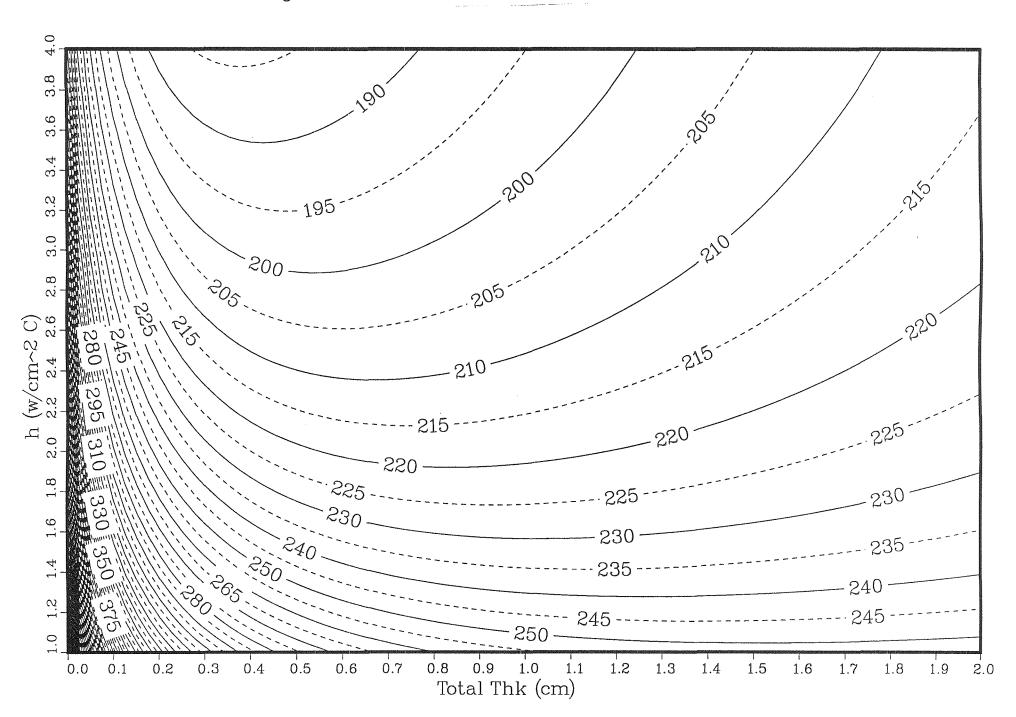


Figure 3: Maximum Cooling Channel Wall Temperature (PS1)

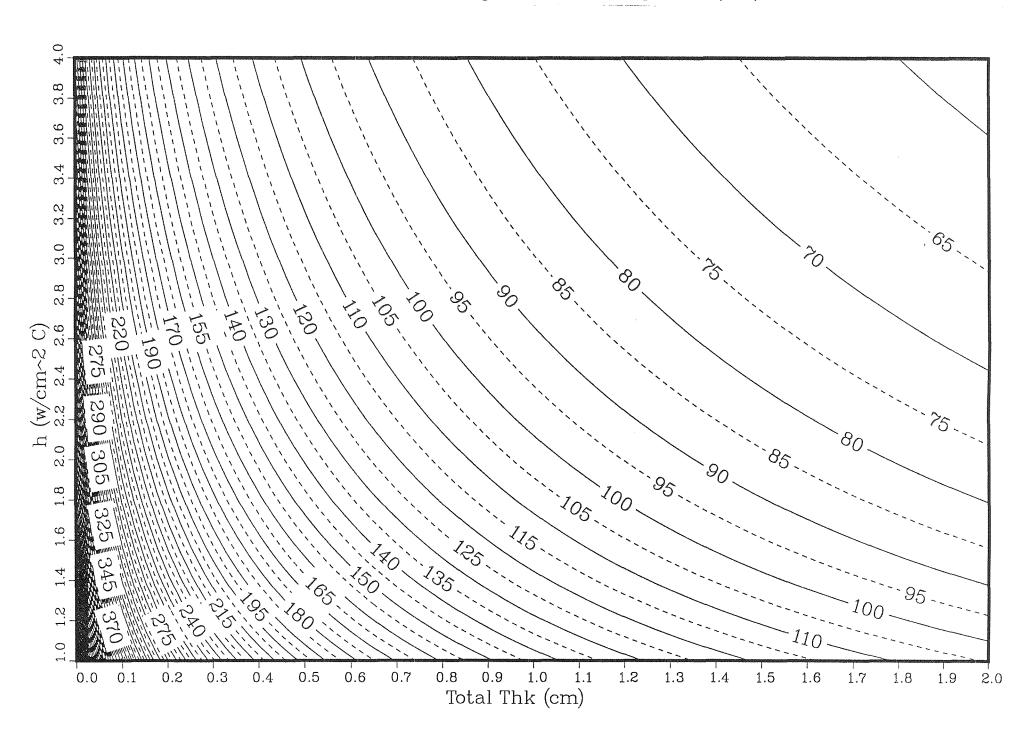


Figure 4: Maximum Effective Stress (Mpa) for Glidcop (PS1)

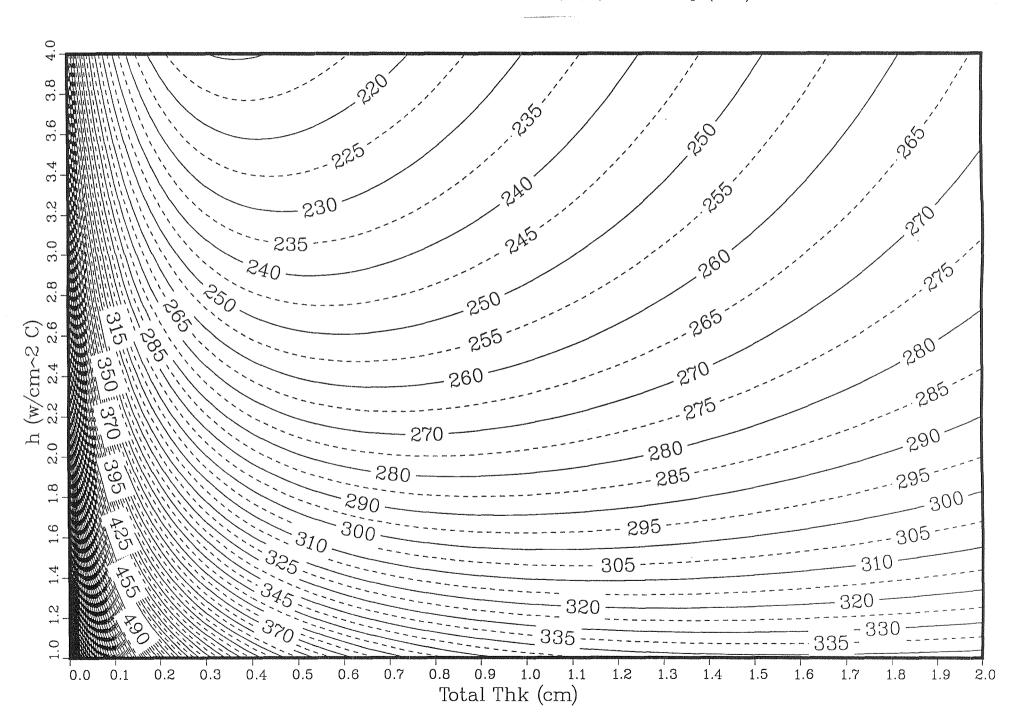


Figure 5: Maximum Temperature at Bonding Surface (OFC) (PS1)

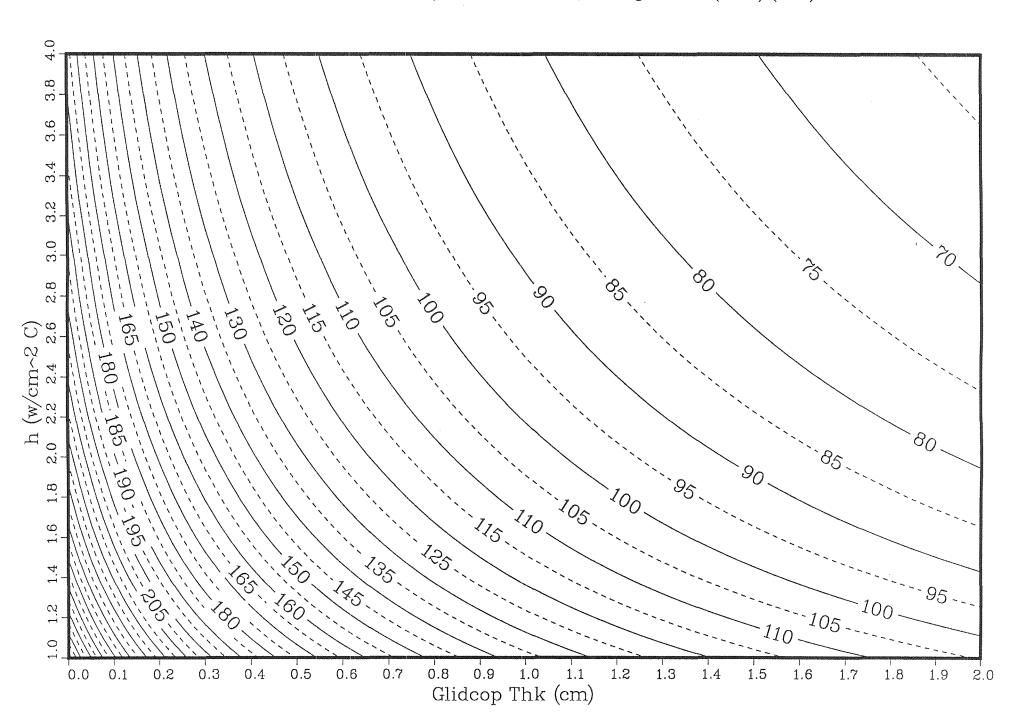
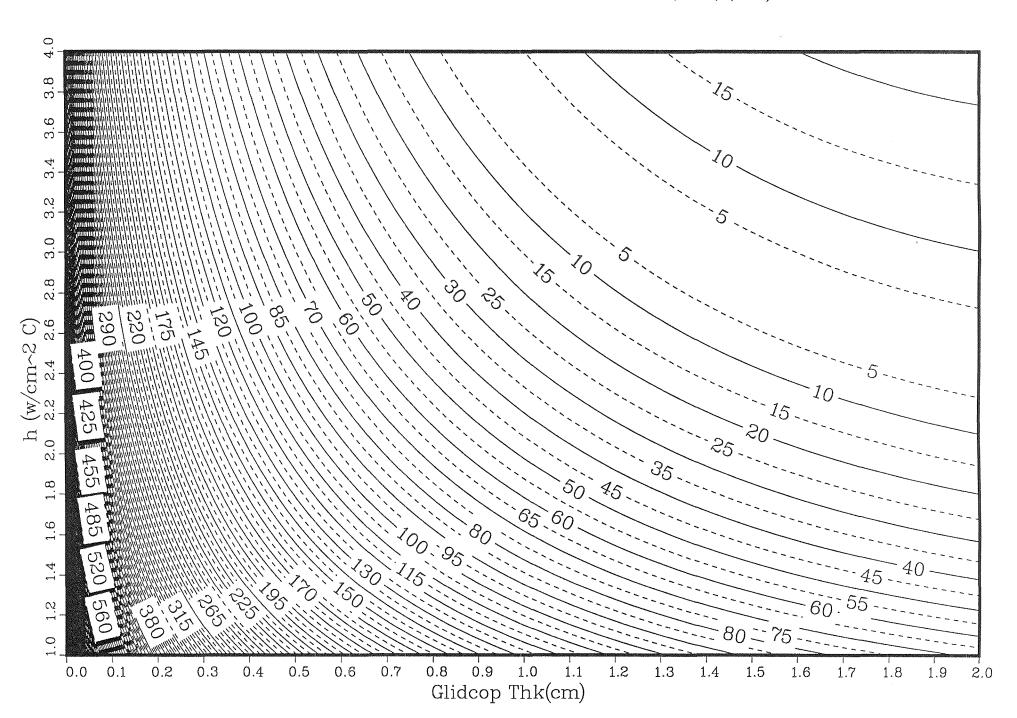


Figure 6: Maximum Effective Stress at Bonding Surface (OFC) (PS1)



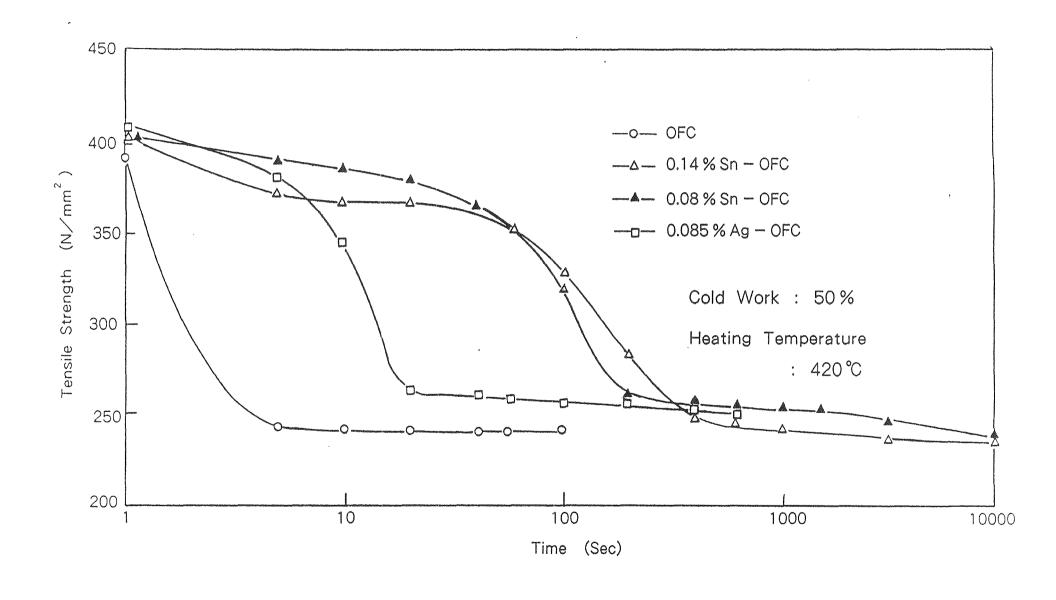


Figure 7: Isothermal Softening Curves for OFC, SN-OFC and Ag-OFC

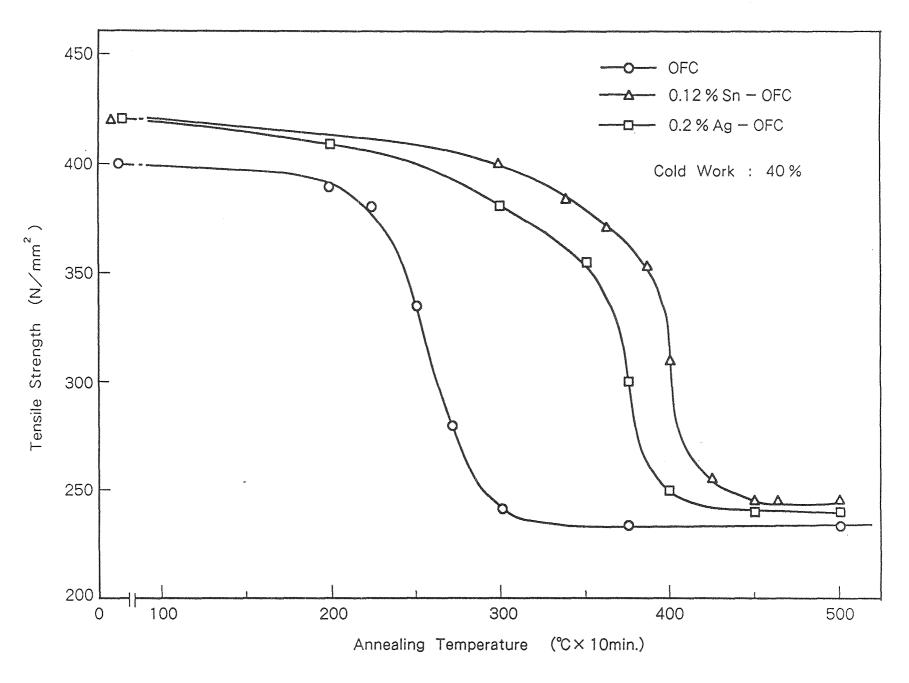
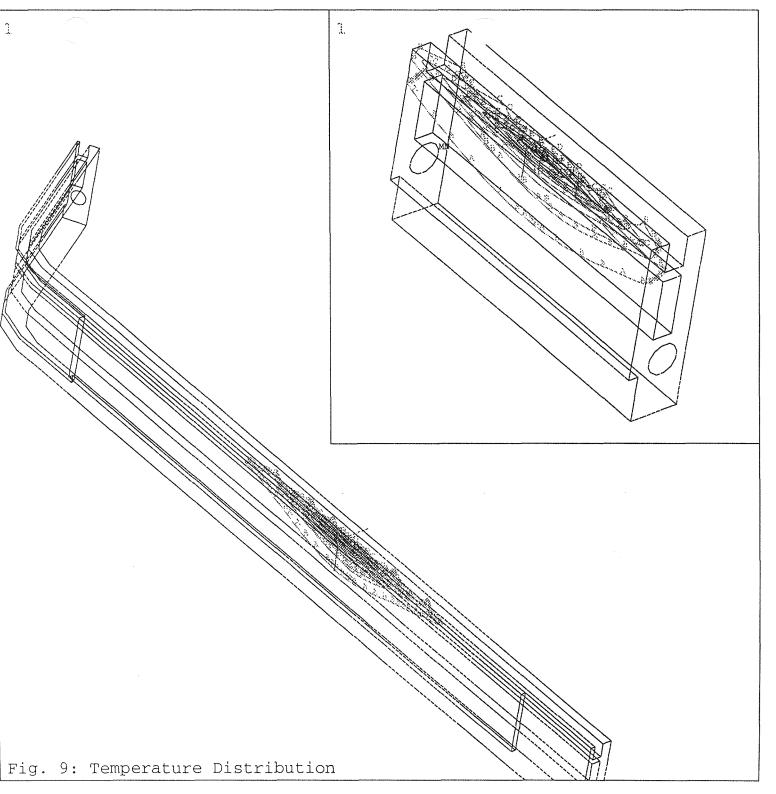


Figure 8: Softening Curves for OFC, Sn-OFC and Ag-OFC



Photon Shutter 1 h=3W/cm^2 C Max q=13 W/mm^2 Dist=18 m Ang=1.5 Deg. .125" Glidcop .125" OFC

Min T = 32.4 C
Max T = 185.5 C
A = 41 C
B = 58 C
C = 75 C
D = 92 C
E = 109 C
F = 126 C
G = 143 C
H = 160 C
I = 177 C

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